

Title (en)

METHOD AND APPARATUS FOR ELECTROLESS PLATING

Publication

**EP 0141507 A3 19850710 (EN)**

Application

**EP 84306103 A 19840906**

Priority

GB 8324060 A 19830908

Abstract (en)

[origin: EP0141507A2] An electroless plating process in which an article is plated while immersed in a plating solution containing a plating metal such as nickel and a reducing agent such as hypophosphate is modified by applying an electrical potential difference between the article, as cathode, and an anode in electrical contact with the plating solution. The current density is generally far below that required to cause electroplating and preferably is 0.01 to 0.05 A/dm<sup>2</sup> on the cathodic article surface.

IPC 1-7

**C23C 18/16**; **C23C 18/34**

IPC 8 full level

**C23C 18/36** (2006.01); **C23C 18/52** (2006.01)

CPC (source: EP)

**C23C 18/36** (2013.01); **C23C 18/52** (2013.01)

Citation (search report)

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Designated contracting state (EPC)

BE DE FR GB IT NL

DOCDB simple family (publication)

**EP 0141507 A2 19850515**; **EP 0141507 A3 19850710**; GB 8324060 D0 19831012

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